

## Maximum Ratings @TA = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	RS3 A/AB	RS3 B/BB	RS3 D/DB	RS3 G/GB	RS3 J/JB	RS3 K/KB	RS3 M/MB	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 4)	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T <sub>T</sub> = 75°C	lo				3.0				Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>				100				Α

### **Thermal Characteristics**

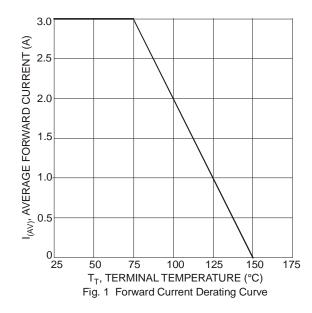
Characteristic		Symbol	Value	Unit
Typical Thermal Resistance Junction to Terminal (Note 5)	SMB SMC	$R_{ heta JT}$	25 11	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-65 to +150	°C

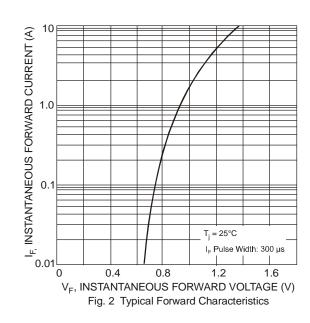
# Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	RS3 A/AB	RS3 B/BB	RS3 D/DB	RS3 G/GB	RS3 J/JB	RS3 K/KB	RS3 M/MB	Unit
Forward Voltage	@ $I_F = 3.0A$	$V_{FM}$				1.3				V
Peak Reverse Current	@ $T_A = 25^{\circ}C$					5.0				^
at Rated DC Blocking Voltage (Note 4	@ $T_A = 125^{\circ}C$	25°C   I <sub>RM</sub>   250			μА					
Maximum Recovery Time (Note 6)		t <sub>rr</sub>		15	50		250	50	00	ns
Typical Total Capacitance (Note 7)		Ст				50				pF

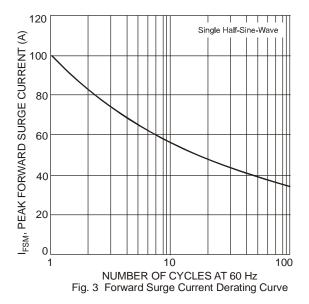
Notes:

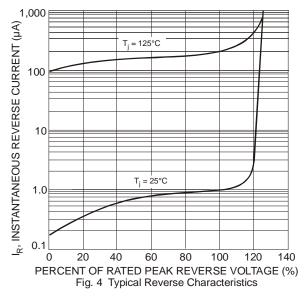
- 4. Short duration pulse test used to minimize self-heating effect.
- 5. Thermal Resistance: Junction to terminal, unit mounted on PC board with 5.0 mm $^2$  (0.013 mm thick) copper pads as heat sink. 6. Reverse recovery test conditions:  $I_F = 0.5A$ ,  $I_R = 1.0A$ ,  $I_{I_T} = 0.25A$ . See Figure 5. 7. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

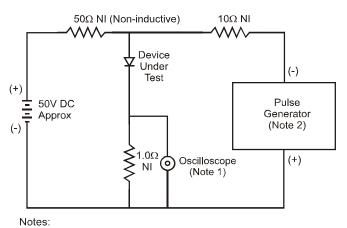


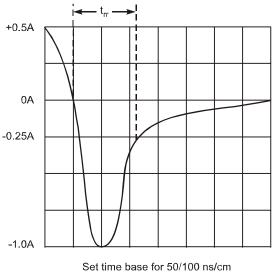








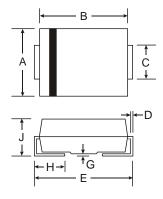




- 1. Rise Time = 7.0ns max. Input Impedance =  $1.0M\Omega$ , 22pF.
- 2. Rise Time = 10ns max. Input Impedance =  $50\Omega$ .

Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

## **Package Outline Dimensions**

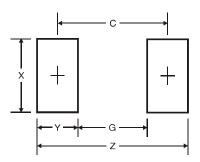


	SMB				
Dim	Min	Max			
Α	3.30	3.94			
В	4.06	4.57			
С	1.96	2.21			
D	0.15	0.31			
E	5.00	5.59			
G	0.05	0.20			
Н	0.76	1.52			
J	2.00	2.50			
All Dim	All Dimensions in mm				

SMC				
Dim	Min	Max		
Α	5.59	6.22		
В	6.60	7.11		
С	2.75	3.18		
D	0.15	0.31		
Е	7.75	8.13		
G	0.10	0.20		
Н	0.76	1.52		
J	2.00	2.50		
All Dimensions in mm				



### **Suggested Pad Layout**



SMB Dimensions	Value (in mm)
Z	6.7
G	1.8
Х	2.3
Υ	2.5
С	4.3

SMC Dimensions	Value (in mm)
Z	9.3
G	4.4
Х	3.3
Υ	2.5
С	6.8

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